

APPENDIX

Changes to Claims:

Claims 2, 8, 11 and 19-25 is canceled.

The following are marked-up versions of the amended claims:

1. (~~Twice~~ Amended) A substrate for semiconductor apparatus, comprising:
a substrate main body having a delineated mounting surface for mounting the semiconductor device;
a plurality of leads formed on the mounting surface, the plurality of lead radially extending from a peripheral area toward a central area of the substrate main body; and
a plurality of conduction sections each defining at least part of an external terminal with substantially rectangular contour lines, the conduction sections being electrically connected to the leads, wherein the substrate main body includes a plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads, such that as the substrate main body is cut along predetermined through-holes, remaining through-holes of the substrate main body define the conduction sections.

7. (~~Twice-Three Times~~ Amended) A semiconductor apparatus, comprising:
a semiconductor device having a plurality of electrodes;
a substrate main body;
a plurality of leads formed on the substrate main body, the plurality of leads radially extending from a peripheral area toward a central area of the substrate main body;
and

a plurality of conduction sections formed on the substrate main body with substantially rectangular contour lines, the conduction sections being electrically connected to the leads, and one of the conduction sections defining an external terminal, wherein the substrate main body includes a plurality of through-holes, internal surfaces of the through-

holes are conductive and connected to respective leads, such that as the substrate main body is cut along predetermined through-holes, remaining through-holes of the substrate main body define the conduction sections.